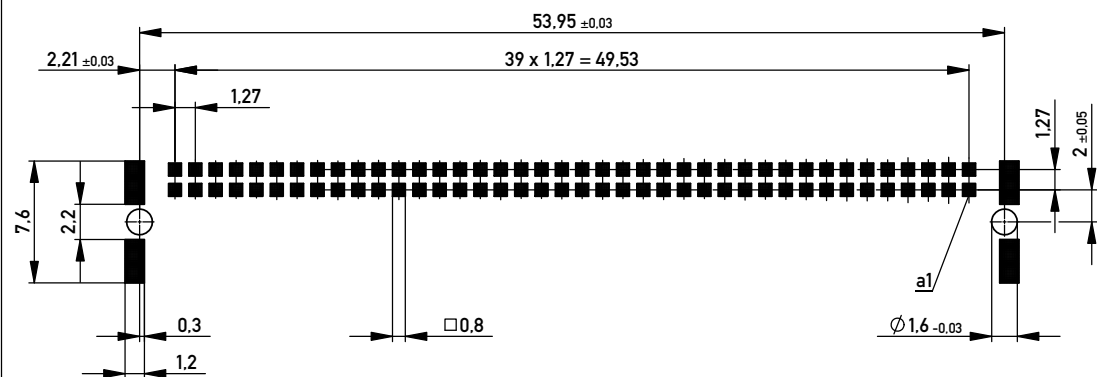


Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT



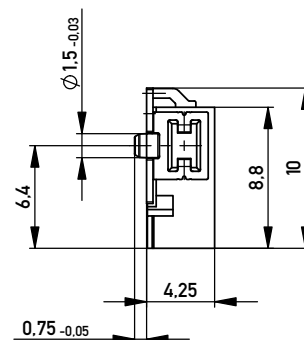
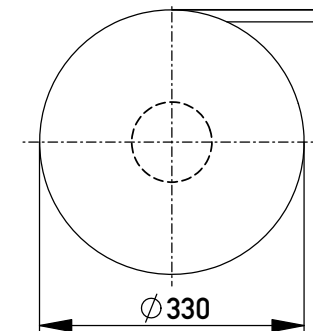
Anforderungsstufe 1  
Performance Level 1

Kontaktbereich vergoldet  
Mating Area gold plating

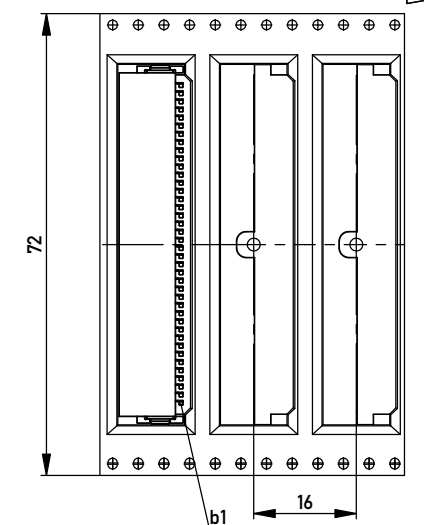
Anschlussbereich verzinkt 4-6 µm  
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm  
Coplanarity Area of Termination ≤ 0,1 mm

Verpackt in Gurtverpackung  
Tape on Reel Packaging  
Verpackungseinheit: 560 Stück  
Packaging unit: 560 pcs



Abspulrichtung - Reel off Direction



BA7-03 - Standard Bauhöhe  
type7-03 - Standard Assembly Height

Information:	Tolerances	 All Dimensions in mm	Scale	3:1
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Subject to modification without prior notice. Drawing will not be updated.	Designation		<b>Messertl. SMC-B 80-SMD-BA7-03</b> <b>Male SMC-B 80-SMD-type7-03</b>	
	www.ERNI.com		<b>154767</b>	
d	02.09.2013	Class		SMCB
Index	Date			I A3

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